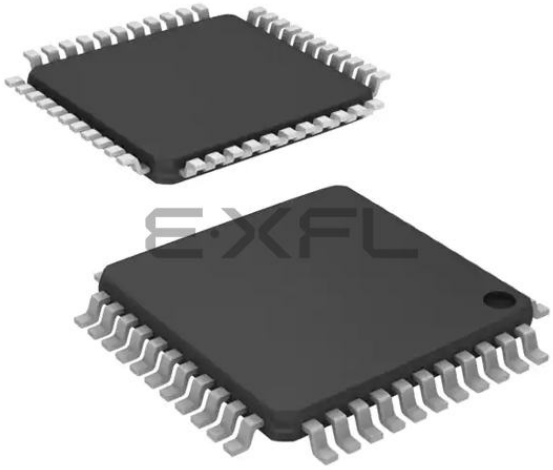

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx230f064d-i-pt

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/36/44-pin Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 "External Oscillator Pins"**)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

REGISTER 5-2: NVMKEY: PROGRAMMING UNLOCK REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<31:24>							
23:16	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<23:16>							
15:8	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<15:8>							
7:0	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMKEY<31:0>:** Unlock Register bits
These bits are write-only, and read as '0' on any read

Note: This register is used as part of the unlock sequence to prevent inadvertent writes to the PFM.

REGISTER 5-3: NVMADDR: FLASH ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMADDR<31:0>:** Flash Address bits
Bulk/Chip/PFM Erase: Address is ignored.
Page Erase: Address identifies the page to erase.
Row Program: Address identifies the row to program.
Word Program: Address identifies the word to program.

REGISTER 7-6: IPCx: INTERRUPT PRIORITY CONTROL REGISTER (CONTINUED)

bit 9-8 **IS01<1:0>:** Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-2 **IP00<2:0>:** Interrupt Priority bits
111 = Interrupt priority is 7
•
•
•
010 = Interrupt priority is 2
001 = Interrupt priority is 1
000 = Interrupt is disabled

bit 1-0 **IS00<1:0>:** Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0

Note:	This register represents a generic definition of the IPCx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 10-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS
	BTSEF	BMXEF	DMAEF(1)	BTOEF(2)	DFN8EF	CRC16EF	CRC5EF(4) / EOFEF(3,5)	PIDEF

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **BTSEF:** Bit Stuff Error Flag bit
- 1 = Packet rejected due to bit stuff error
- 0 = Packet accepted

bit 6 **BMXEF:** Bus Matrix Error Flag bit
- 1 = The base address, of the Buffer Descriptor Table, or the address of an individual buffer pointed to by a Buffer Descriptor Table entry, is invalid.
- 0 = No address error

bit 5 **DMAEF:** DMA Error Flag bit(1)
- 1 = USB DMA error condition detected
- 0 = No DMA error

bit 4 **BTOEF:** Bus Turnaround Time-Out Error Flag bit(2)
- 1 = Bus turnaround time-out has occurred
- 0 = No bus turnaround time-out

bit 3 **DFN8EF:** Data Field Size Error Flag bit
- 1 = Data field received is not an integral number of bytes
- 0 = Data field received is an integral number of bytes

bit 2 **CRC16EF:** CRC16 Failure Flag bit
- 1 = Data packet rejected due to CRC16 error
- 0 = Data packet accepted

Note 1: This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

REGISTER 10-14: U1FRMH: USB FRAME NUMBER HIGH REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	R-0	R-0	R-0
	—	—	—	—	—	FRMH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-3 **Unimplemented:** Read as '0'

bit 2-0 **FRMH<2:0>:** The Upper 3 bits of the Frame Numbers bits
The register bits are updated with the current frame number whenever a SOF TOKEN is received.

REGISTER 10-15: U1TOK: USB TOKEN REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PID<3:0>(1)				EP<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-4 **PID<3:0>:** Token Type Indicator bits(1)
1101 = SETUP (TX) token type transaction
1001 = IN (RX) token type transaction
0001 = OUT (TX) token type transaction
Note: All other values are reserved and must not be used.

bit 3-0 **EP<3:0>:** Token Command Endpoint Address bits
The four bit value must specify a valid endpoint.

Note 1: All other values are reserved and must not be used.

NOTES:

REGISTER 19-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 5 **ABAUD:** Auto-Baud Enable bit
1 = Enable baud rate measurement on the next character – requires reception of Sync character (0x55); cleared by hardware upon completion
0 = Baud rate measurement disabled or completed

bit 4 **RXINV:** Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'

bit 3 **BRGH:** High Baud Rate Enable bit
1 = High-Speed mode – 4x baud clock enabled
0 = Standard Speed mode – 16x baud clock enabled

bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits
11 = 9-bit data, no parity
10 = 8-bit data, odd parity
01 = 8-bit data, even parity
00 = 8-bit data, no parity

bit 0 **STSEL:** Stop Selection bit
1 = 2 Stop bits
0 = 1 Stop bit

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 20-1: PMCON: PARALLEL PORT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON(1)	—	SIDL	ADRMUX<1:0>		PMPTTL	PTWREN	PTRDEN
7:0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0
	CSF<1:0>(2)		ALP(2)	—	CS1P(2)	—	WRSP	RDSP

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Parallel Master Port Enable bit(1)
- 1 = PMP enabled
- 0 = PMP disabled, no off-chip access performed

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue module operation when the device enters Idle mode
- 0 = Continue module operation when the device enters Idle mode

bit 12-11 **ADRMUX<1:0>:** Address/Data Multiplexing Selection bits
- 11 = Lower 8 bits of address are multiplexed on PMD<7:0> pins; upper 8 bits are not used
- 10 = All 16 bits of address are multiplexed on PMD<7:0> pins
- 01 = Lower 8 bits of address are multiplexed on PMD<7:0> pins, upper bits are on PMA<10:8> and PMA<14>
- 00 = Address and data appear on separate pins

bit 10 **PMPTTL:** PMP Module TTL Input Buffer Select bit
- 1 = PMP module uses TTL input buffers
- 0 = PMP module uses Schmitt Trigger input buffer

bit 9 **PTWREN:** Write Enable Strobe Port Enable bit
- 1 = PMWR/PMENB port enabled
- 0 = PMWR/PMENB port disabled

bit 8 **PTRDEN:** Read/Write Strobe Port Enable bit
- 1 = PMRD/PMWR port enabled
- 0 = PMRD/PMWR port disabled

bit 7-6 **CSF<1:0>:** Chip Select Function bits(2)
- 11 = Reserved
- 10 = PMCS1 functions as Chip Select
- 01 = PMCS1 functions as PMA<14>
- 00 = PMCS1 functions as PMA<14>

bit 5 **ALP:** Address Latch Polarity bit(2)
- 1 = Active-high (PMALL and PMALH)
- 0 = Active-low ($\overline{\text{PMALL}}$ and $\overline{\text{PMALH}}$)

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON control bit.

2: These bits have no effect when their corresponding pins are used as address lines.

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
	ALRMEN(1,2)	CHIME(2)	PIV(2)	ALRMSYNC(3)	AMASK<3:0>(2)			
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ARPT<7:0>(2)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ALRMEN:** Alarm Enable bit(1,2)
- 1 = Alarm is enabled
- 0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit(2)
- 1 = Chime is enabled – ARPT<7:0> is allowed to rollover from 0x00 to 0xFF
- 0 = Chime is disabled – ARPT<7:0> stops once it reaches 0x00

bit 13 **PIV:** Alarm Pulse Initial Value bit(2)

When ALRMEN = 0, PIV is writable and determines the initial value of the Alarm Pulse.
When ALRMEN = 1, PIV is read-only and returns the state of the Alarm Pulse.

bit 12 **ALRMSYNC:** Alarm Sync bit(3)
- 1 = ARPT<7:0> and ALRMEN may change as a result of a half second rollover during a read. The ARPT must be read repeatedly until the same value is read twice. This must be done since multiple bits may be changing, which are then synchronized to the PB clock domain
- 0 = ARPT<7:0> and ALRMEN can be read without concerns of rollover because the prescaler is > 32 RTC clocks away from a half-second rollover

bit 11-8 **AMASK<3:0>:** Alarm Mask Configuration bits(2)
- 0000 = Every half-second
- 0001 = Every second
- 0010 = Every 10 seconds
- 0011 = Every minute
- 0100 = Every 10 minutes
- 0101 = Every hour
- 0110 = Once a day
- 0111 = Once a week
- 1000 = Once a month
- 1001 = Once a year (except when configured for February 29, once every four years)
- 1010 = Reserved; do not use
- 1011 = Reserved; do not use
- 11xx = Reserved; do not use

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note: This register is reset only on a Power-on Reset (POR).

TABLE 22-1: ADC REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9120	ADC1BUFB	31:16	ADC Result Word B (ADC1BUFB<31:0>)																0000
		15:0																	0000
9130	ADC1BUFC	31:16	ADC Result Word C (ADC1BUFC<31:0>)																0000
		15:0																	0000
9140	ADC1BUFD	31:16	ADC Result Word D (ADC1BUFD<31:0>)																0000
		15:0																	0000
9150	ADC1BUFE	31:16	ADC Result Word E (ADC1BUFE<31:0>)																0000
		15:0																	0000
9160	ADC1BUFF	31:16	ADC Result Word F (ADC1BUFF<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for details.

REGISTER 22-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

REGISTER 23-1: CMXCON: COMPARATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	R-0
	ON(1)	COE	CPOL(2)	—	—	—	—	COUT
7:0	R/W-1	R/W-1	U-0	R/W-0	U-0	U-0	R/W-1	R/W-1
	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator ON bit(1)
- 1 = Module is enabled. Setting this bit does not affect the other bits in this register
- 0 = Module is disabled and does not consume current. Clearing this bit does not affect the other bits in this register

bit 14 **COE:** Comparator Output Enable bit
- 1 = Comparator output is driven on the output CxOUT pin
- 0 = Comparator output is not driven on the output CxOUT pin

bit 13 **CPOL:** Comparator Output Inversion bit(2)
- 1 = Output is inverted
- 0 = Output is not inverted

bit 12-9 **Unimplemented:** Read as '0'

bit 8 **COUT:** Comparator Output bit
- 1 = Output of the Comparator is a '1'
- 0 = Output of the Comparator is a '0'

bit 7-6 **EVPOL<1:0>:** Interrupt Event Polarity Select bits
- 11 = Comparator interrupt is generated on a low-to-high or high-to-low transition of the comparator output
- 10 = Comparator interrupt is generated on a high-to-low transition of the comparator output
- 01 = Comparator interrupt is generated on a low-to-high transition of the comparator output
- 00 = Comparator interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Positive Input Configure bit
- 1 = Comparator non-inverting input is connected to the internal CVREF
- 0 = Comparator non-inverting input is connected to the CXINA pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Negative Input Select bits for Comparator
- 11 = Comparator inverting input is connected to the IVREF
- 10 = Comparator inverting input is connected to the CxIND pin
- 01 = Comparator inverting input is connected to the CxINC pin
- 00 = Comparator inverting input is connected to the CxINB pin

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: Setting this bit will invert the signal to the comparator interrupt generator as well. This will result in an interrupt being generated on the opposite edge from the one selected by EVPOL<1:0>.

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD}) (Notes 1, 5)					
DC40k	44	70	μA	-40°C	Base Power-Down Current
DC40l	44	70	μA	+25°C	
DC40n	168	259	μA	+85°C	
DC40m	335	536	μA	+105ºC	
Module Differential Current					
DC41e	5	20	μA	3.6V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC42e	23	50	μA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC43d	1000	1100	μA	3.6V	ADC: ΔI_{ADC} **(Notes 3,4)**

Note 1: The test conditions for I_{PD} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}
- RTCC and JTAG are disabled

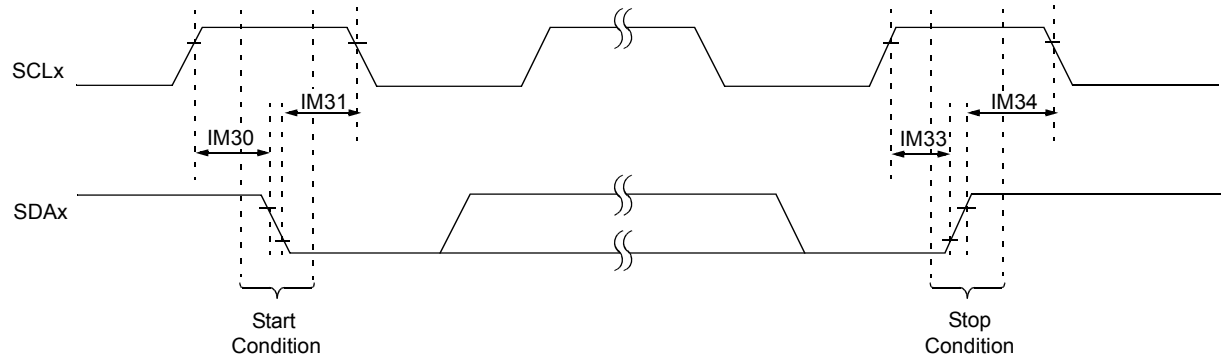
2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: I_{PD} electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

FIGURE 30-14: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-15: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)

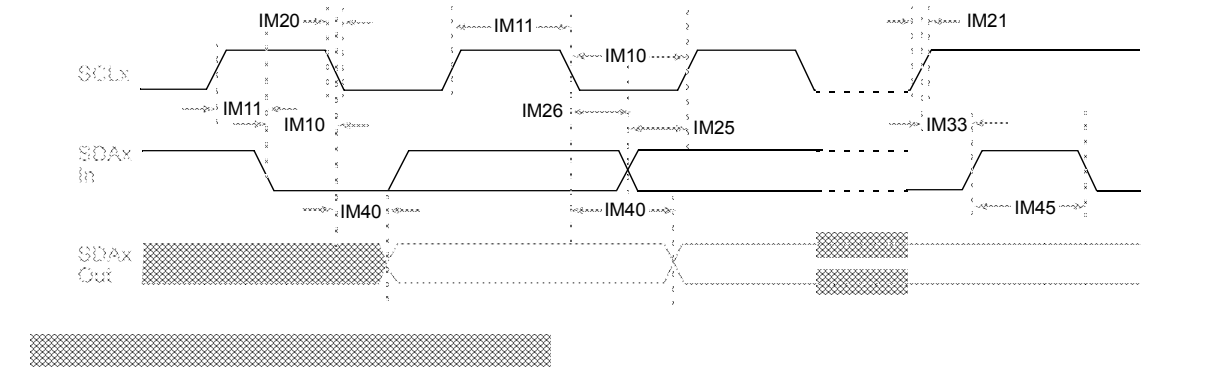


TABLE 30-34: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 5): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of VDD – 0.3 or 2.5	—	Lesser of VDD + 0.3 or 3.6	V	—
AD02	AVSS	Module VSS Supply	VSS	—	AVDD	V	**(Note 1)**
Reference Inputs							
AD05 AD05a	VREFH	Reference Voltage High	AVSS + 2.0 2.5	— —	AVDD 3.6	V V	**(Note 1)** VREFH = AVDD **(Note 3)**
AD06	VREFL	Reference Voltage Low	AVSS	—	VREFH – 2.0	V	**(Note 1)**
AD07	VREF	Absolute Reference Voltage (VREFH – VREFL)	2.0	—	AVDD	V	**(Note 3)**
AD08 AD08a	IREF	Current Drain	— —	250 —	400 3	µA µA	ADC operating ADC off
Analog Input							
AD12	VINH-VINL	Full-Scale Input Span	VREFL	—	VREFH	V	—
AD13	VINL	Absolute VINL Input Voltage	AVSS – 0.3	—	AVDD/2	V	—
AD14	VIN	Absolute Input Voltage	AVSS – 0.3	—	AVDD + 0.3	V	—
AD15	—	Leakage Current	—	±0.001	±0.610	µA	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V Source Impedance = 10 kΩ
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	5k	Ω	**(Note 1)**
ADC Accuracy – Measurements with External VREF+/VREF-							
AD20c	Nr	Resolution	10 data bits			bits	—
AD21c	INL	Integral Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V
AD22c	DNL	Differential Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V **(Note 2)**
AD23c	GERR	Gain Error	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V
AD24c	EOFF	Offset Error	> -1	—	< 1	Lsb	VINL = AVSS = 0V, AVDD = 3.3V
AD25c	—	Monotonicity	—	—	—	—	Guaranteed

Note 1: These parameters are not characterized or tested in manufacturing.

2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with a 1 kHz sine wave.

5: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

FIGURE 32-3: TYPICAL IPD CURRENT @ VDD = 3.3V

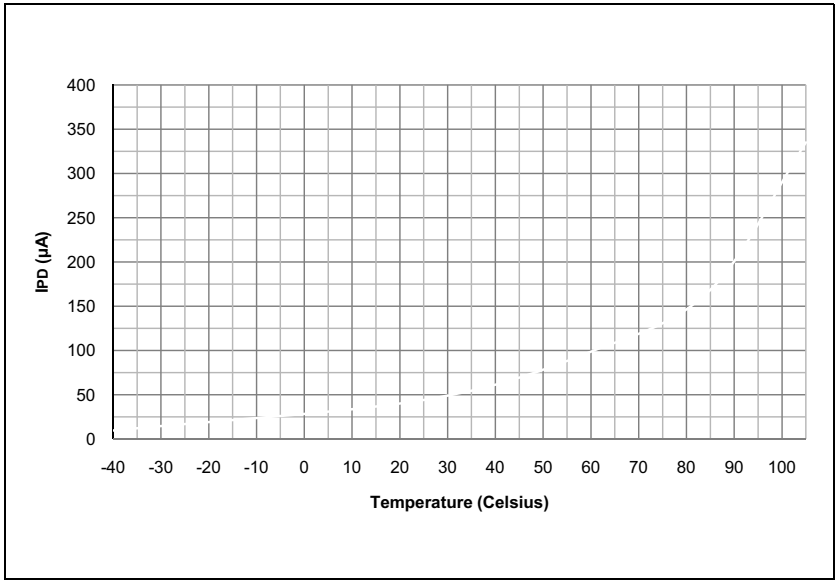


FIGURE 32-4: TYPICAL IDD CURRENT @ VDD = 3.3V

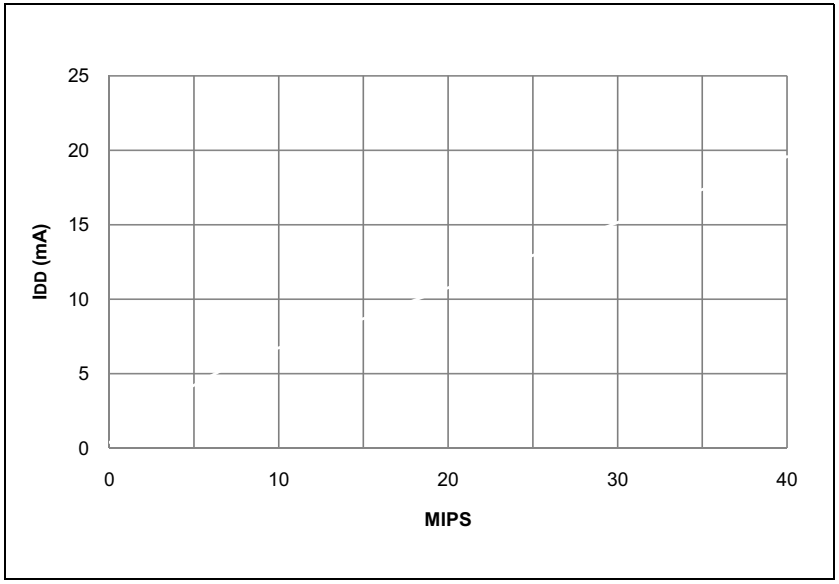
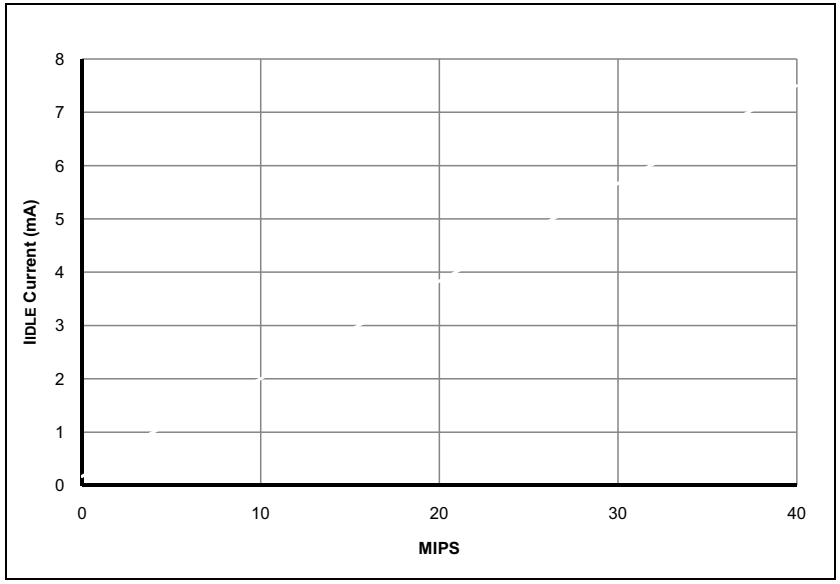


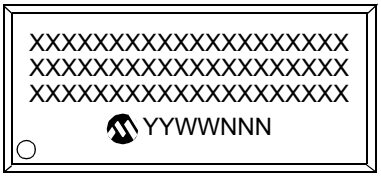
FIGURE 32-5: TYPICAL IIDLE CURRENT @ VDD = 3.3V



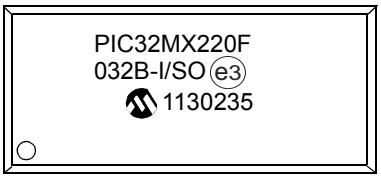
33.0 PACKAGING INFORMATION

33.1 Package Marking Information

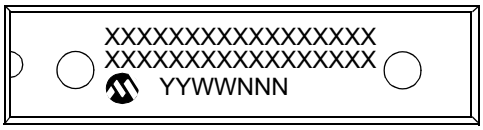
28-Lead SOIC



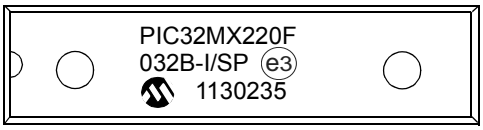
Example



28-Lead SPDIP



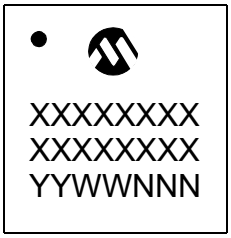
Example



28-Lead SSOP

Example

28-Lead QFN



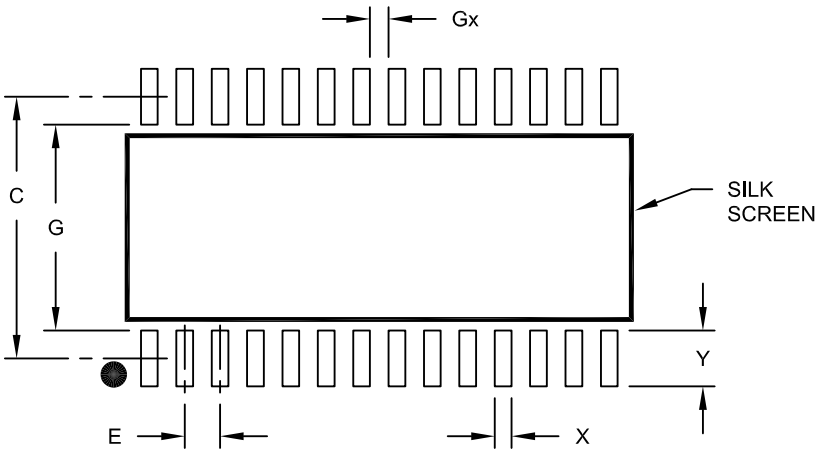
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX230F256B
- PIC32MX130F256D
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in Table A-6, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams).
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Updated these sections: **2.2 "Decoupling Capacitors"**, **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**, **2.4 "Master Clear (MCLR) Pin"**, **2.8.1 "Crystal Oscillator Design Consideration"**
4.0 "Memory Organization"	Added Memory Map for new devices (see Figure 4-6).
14.0 "Watchdog Timer (WDT)"	New chapter created from content previously located in the Special Features chapter.
30.0 "Electrical Characteristics"	Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12.

Revision H (July 2015)

This revision includes the following major changes as described in Table A-7, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

Section	Update Description
2.0 "Guidelines for Getting Started with 32-bit MCUs"	**Section 2.9 "Sosc Design Recommendation"** was removed.
8.0 "Oscillator Configuration"	The Primary Oscillator (POSC) logic in the Oscillator diagram was updated (see Figure 8-1).
30.0 "Electrical Characteristics"	The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). **Table 30-9: "DC Characteristics: I/O Pin Input Injection current Specifications"** was added.